

### **Amendments to the Claims**

Claim 1 (**Currently Amended**) A wafer handling checker comprising:

a plurality of training operation wafers each formed of a semiconductor or ceramics to which a conductive film is applied on a face thereof, or a material having conductive properties;

a cassette having a plurality of slots for housing the plurality of training operation wafers, and a plurality of electrodes for contacting the plurality of training operation wafers when the plurality of training operation wafers are inserted into the plurality of slots;

a vacuum pincette having a conductive suction part for operating on the plurality of training operation wafers;

voltage application means for applying a voltage between each electrode of the cassette and the conductive suction part of the vacuum pincette; and

state detection means for detecting which of the plurality of training operation wafers housed in the cassette the vacuum pincette is in contact between the vacuum pincette and each training operation wafer with by detecting a potential of each electrode of the cassette or a current flowing to an electrode of the cassette associated with the contacted training operation wafer.

Claim 2 (**Previously Presented**) The wafer handling checker according to Claim 1, wherein the cassette has display means for specifying a training operation wafer to be operated on based on operation specification information.

Claim 3 (**Previously Presented**) The wafer handling checker according to Claim 2, further comprising decision means for deciding whether an erroneous operation occurs based on a result of detection by the state detection means and the operation specification information.

Claim 4 (**Previously Presented**) The wafer handling checker according to Claim 3, wherein the decision means has output means for generating sound when the decision means decides the erroneous operation has occurred.

Claim 5 (**Currently Amended**) A wafer handling checker comprising:

a plurality of training operation wafers each formed of a semiconductor or ceramics to which a conductive film is applied on a face thereof, or a material having conductive properties;

a cassette having a plurality of slots for housing the plurality of training operation wafers, and a plurality of electrodes for contacting the plurality of training operation wafers when the plurality of training operation wafers are inserted into the plurality of slots;

a vacuum pincette having a conductive suction part for operating on the plurality of training operation wafers; and

a controller operable to apply a voltage between each electrode of the cassette and the conductive suction part of the vacuum pincette, and detect which of the plurality of training operation wafers housed in the cassette the vacuum pincette is in contact ~~between the vacuum pincette and each training operation wafer~~ with by detecting a potential of each electrode of the cassette or a current flowing to an electrode of the cassette associated with the contacted training operation wafer.

Claim 6 (**Previously Presented**) The wafer handling checker according to Claim 5, wherein the cassette has a display operable to specify a training operation wafer to be operated on based on operation specification information.

Claim 7 (**Previously Presented**) The wafer handling checker according to Claim 6, wherein the controller is further operable to decide whether an erroneous operation occurs based on a result of detection and the operation specification information.

Claim 8 (**Previously Presented**) The wafer handling checker according to Claim 7, wherein the controller is further operable to cause a sound to be generated when the erroneous operation has occurred.